

Organisational Information

For registration please use the registration form which is available on the ECPE web page: www.ecpe.org
> ECPE Events > ECPE Workshop: Reliability Engineering - 10 Years Robustness Validation > Registration Form

www.ecpe.org/ecpe-events

Deadline for registration:

- **17 January 2018**

Participation fee:

- **€ 595,-** * for industry
- **€ 445,-** * for universities/institutes
- **€ 150,-** * for students/PhD students
(copy of student ID requested)
(limited number only)
(optional dinner: € 50,-* extra fee)

*plus 19 % VAT

- The participation fee includes dinner, lunches, coffee/soft drinks and a flash drive with the workshop presentations. Students/PhD students can book the dinner for an extra fee of € 50,-*
- A printed version of the workshop handout is available on request (€ 50,-*).
- With the confirmation of registration by email you are registered for the workshop and the invoice will be sent by post.
- Three participants from each ECPE member company free of charge. Allocation in sequence of registration.
- Further information (hotel list and maps) will be provided after registration and is available on the ECPE web page.
- In case of cancellation later than two weeks before beginning or non-attendance 50 % of the participation fee is payable.

Organisational Information

Organiser	ECPE e.V. 90443 Nuremberg, Germany www.ecpe.org
Chairmen	Prof. Eckhard Wolfgang ECPE e.V. Dr. Jörg Breibach Robert Bosch
Organisation	Lena Somschor, ECPE e.V. +49 911 81 02 88 – 18 lena.somschor@ecpe.org
Venue	Filderhalle Bahnhofstr. 61 70771 Leinfelden-Echterdingen Germany +49 711 758575-0 info@filderhalle.de www.filderhalle.de



Source: Filderhalle Leinfelden-Echterdingen GmbH



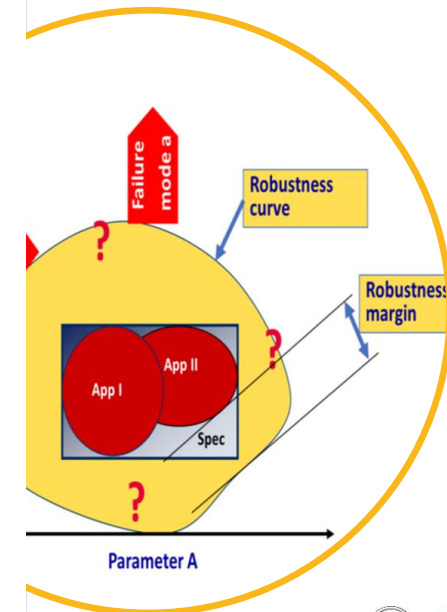
Draft Programme

ECPE Workshop

Reliability Engineering 10 Years Robustness Validation

24 - 25 January 2018
Filderhalle
Leinfelden-Echterdingen
Germany

in cooperation with



BOSCH
Invented for life



ECPE Workshop

Reliability Engineering 10 Years Robustness Validation

24 - 25 January 2018

Leinfelden-Echterdingen, Germany

What has been achieved and what are the main challenges?

The first handbooks on Robustness Validation were available in the years 2006/07. They were worked out by the German ZVEI, the US SAE and the Japanese SAE.

They describe a process how to design, develop, manufacture and test electronic devices, components and systems. It is a process based on the knowledge of:

- the conditions of use (mission profile),
- the failure mechanisms,
- and of accelerated models needed for accelerated tests

This involves a paradigm shift from "test for standards" to "test-to-fail". The Physics-of-failure and End-of-life test approach requires a lot of new strategies and methods, which will be discussed by OEMs, 1st Tiers and 2nd Tiers as well as Academia.

To underline the character of a workshop two Panel discussions are dealing with:

- Design and Technology
- What about the future?

Finally it will be discussed how future may look like.

The workshop is chaired by:
Prof. Eckhard Wolfgang, ECPE
Dr. Jörg Breibach, Robert Bosch
Thomas Harder, ECPE

All presentations and discussions will be in English language.

Programme

Wednesday, 24 January 2018

9:30 Start of Registration / Welcome Coffee

10:00 Welcome, Opening

Eckhard Wolfgang, Thomas Harder, ECPE (D)
Jörg Breibach, Robert Bosch (D)

10:20 Robustness Validation Overview

Andreas Preussger, Preussger Consulting (D)

RV: Application Environment

10:50 Reliability of Automotive LEDs

Wolfgang Pohlmann, Hella (D)

11:20 Reliability of LEDs: Rth vs. Temperature – Impact on Lifetime Modeling

Stefan Schoemaker, OSRAM (D)

11:40 Qualification Extension from Automotive to Harsh Aerospace Mission Profiles

Alberto Mancaloni, STMicroelectronics (I)

12:10 Comprehensive Methodology for Reliability Qualification of Smart Power Technologies

Antonio Andreini, STMicroelectronics (I)

12:40 Synthetic Mission Profiles

Stefan Straube, Fraunhofer IZM (D)

13:10 Lunch

RV: Focus on Requirements and Technology

14:10 Lifetime Modeling Strategies in the Context of Automotive Requirements

Olaf Wittler, Fraunhofer IZM (D)

14:40 RV in Context with AEC100/ 101 Appendix 7 Qualification

Ulrich Abelein, Infineon Technologies (D)

15:10 Robustness Validation of Cu-wire in Semiconductor Devices for High Temperature Automotive Applications

Rene Rongen, NXP Semiconductors (NL)

15:40 Coffee Break

Panel Session "Design and Technology"

16:00 Moderator: Jörg Breibach, Robert Bosch (D)

18:00 End of 1st Workshop Day

19:30 Dinner at Parkhotel Stuttgart Messe-Airport

Programme

Thursday, 25 January 2018

8:30 Start of 2nd Workshop Day

Power Modules and PE Systems

8:30 Power Module and DC-Link Capacitor Qualification

Martin Rittner, Robert Bosch (D); Markus Thoben, Infineon Technologies (D); Kai Kriegel, Siemens (D)

9:00 RV for Industrial Power Modules

Oliver Schilling, Infineon Technologies (D)

9:20 Mission Profile and SiC Module Reliability

Francesco Iannuzzo, CORPE, Univ Aalborg (DK)

9:40 Mission Profile Based System-Level Reliability Analysis of Power Electronic Converters

Huai Wang, CORPE Univ Aalborg (DK)

10:10 Coffee Break

End-of-Life Testing and Physics of Failure PoF

10:30 Monitoring PC and TC Test

Gerard Coquery, VEDECOM (F)

10:50 HALT and HAST Tests

Stefan Schmitt, Semikron (D)

11:10 Simulation Based Derivation of Humidity Load Collectives

Daniel Koenig, Robert Bosch (D)

11:30 Analytics for PoF

Matthias Petzold, Fraunhofer CAM (D)

12:10 Ensuring the Reliability of Power Electronic Devices with Regard to Terrestrial Cosmic Radiation

Gerald Sölkner, Infineon Technologies (D)

12:40 Lunch

What about the Future?

13:40 Resilience - Reliability Engineering after RV

Franz Dietz, Robert Bosch (D)

14:00 Degradation - Self Correcting Systems

Andreas Preussger, Preussger Consulting (D)

14:20 What about Closing the Loop between Target Setting, Design and Field Failures

Peter de Place Rimmen, Danfoss (DK)

Panel Session "What about the Future?"

14:40 Moderator: Werner Kanert, Consultant (D)

15:45 Final Discussion

16:00 End of Workshop